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(71) Applicant(s):

LAN TECHNICAL SERVICE CO., LTD. [JP/JP]; 26-2-32F, Nishi-shinjuku 1-chome, Shinjuku-ku, Tokyo 1630532 (JP) *(for all designated states)*

SUGA Tadatomo [JP/JP]; 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 1640003 (JP) *(for all designated states)*

(72) Inventor(s):

SUGA Tadatomo; 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 1640003 (JP)

MATSUMOTO Yoshiie; 26-2-32F, Nishi-shinjuku 1-chome, Shinjuku-ku, Tokyo 1630532 (JP)

(74) Agent(s):

AKATSU Takeshi; 18-2-102, Sengoku 1-chome, Bunkyo-ku Tokyo 1120011 (JP)

(54) Title (EN): METHOD FOR JOINING TRANSPARENT SUBSTRATES, AND LAMINATED BODY

(54) Title (FR): PROCÉDÉ DE JONCTION DE SUBSTRATS TRANSPARENTS, ET CORPS STRATIFIÉ

(54) Title (JA): 透明基板の接合方法及び積層体

(57) Abstract:

(EN): Provided is a method for joining transparent substrates, the method comprising: preparing a pair of transparent substrates; forming aluminum oxide thin films on joint surfaces of the transparent substrates by sputtering; joining the pair of transparent substrates by bringing the aluminum oxide thin films into contact with air; and heating the pair of joined transparent substrates.

(FR): L'invention concerne un procédé de jonction de substrats transparents, le procédé consistant à : préparer une paire de substrats transparents; former par pulvérisation des films minces d'oxyde d'aluminium sur des surfaces de jonction des substrats transparents; joindre la paire de substrats transparents en amenant les films minces d'oxyde d'aluminium en contact avec l'air; et chauffer la paire de substrats transparents joints.

(JA): 透明基板の接合法であって、1対の透明基板を用意することと、透明基板の接合面に、スパッタリング法により酸化アルミニウムの薄膜を形成することと、酸化アルミニウムの薄膜を大気中で接触させて前記1対の透明基板を接合することと、接合された1対の透明基板を加熱することとを備える。

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